

## APEX 2003 Overview

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## APEX 2003 Overview

- **Keynote Speakers**
- **Acronyms**
- **Free Forums**
- **IPC Standards Development Committees, etc.**
- **Exhibitors**
- **Best Papers**
- **Best Toy of the Show**

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## Keynote Speakers

- **Robert Herbold, Executive Vice President & Chief Operating Officer (Retired), Microsoft Corp.**
  - “A Strategy for Improving Profitability & Agility”
- **James Burke, Author & Science Historian**
  - “Innovation & Change” (1 + 1 = 3)
- **Niels Warburg, University of Stuttgart**
  - “The Science of Lead-Free Manufacturing”

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## Acronyms

- **APEX** – Electronic Assembly Process Exhibition & Conference
- **IPC** – Association Connecting Electronics Industries
- **SMEMA** – Surface Mount Equipment Manufacturers Association
- **TURI** – Toxics Use Reduction Institute
- **NEMI** – National Electronics Manufacturing Initiative

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## Free Forums

### Total of 14 Free Forums

- **Forums of Interest**
  - F01 – Electronics Manufacturing in China
  - F06 – Predicting the Future of Surface Mount Technology Practices (Sponsored by SMT)
  - F12 – Expanding Your Business Overseas: U.S. Government Export Promotion Programs
  - F13 – IPC Technology Roadmap

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## IPC Standards Development Committees, Etc.

- **Standards meetings were well attended this year**
- **Attendance**
  - 7,200 total visitors & exhibitors
  - 650 professional development courses
  - 620 technical conferences (standards committees)
  - 65 Senior level managers - IPC Forum for EMS Executives

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## Exhibitors

- **Focus this Year**
  - Die feeding and taping equipment
  - Die placement equipment

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## Best Papers

- **U.S. Paper**
  - *“Equipment Impacts of Lead Free Wave Soldering”*, Jim Morris, Cookson Equipment & Dr. Matthew J. O’Keefe, University of Missouri
- **International Paper**
  - *“New Insights in Underfill Flow and Flip Chip Reliability”*, Team authored from the Fraunhofer Institute for Reliability & Microintegration in Berlin, Germany

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## Best Toy of the Show

- **Last Year’s Toy**
- **This Year’s Toy**

### Closing

Reference IPC Website for Info

*[www.ipc.org](http://www.ipc.org)*

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